

	Famos	Mitikas
No. of die	1	2
No. of layers in the substrate	11	11
Package ball count	896	1296
Flip-chip or wirebond?	Flip-chip	Wirebond
Pad or bump count (total if multiple die)	12220	9968
Count of D2D signals	NA	
Number of power planes	6	6
Layer(s) used for power planes (add another worksheet to this spreadsheet to capture details if you like)	L3,L5,L5,L6,L7,L8,L9.	L3,L5,L6,L7,L8,L9
Maximum length of D2D signal trace	NA	
Minimum length of D2D signal trace	NA	
Identification of differential pairs: look at signal names and list examples if you find any	49(CK0,CKL,DQS1,PECLK,X22T)	17(CCLK,DOCLK,RCLK_1)
No. of die	1	2